

Title (en)
HOT PLATE AND CONDUCTOR PASTE

Title (de)
HEIZPLATTE UND LEITFÄHIGE PASTE

Title (fr)
PLAQUE CHAUFFANTE ET PÂTE CONDUCTRICE

Publication
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Application
EP 00922933 A 20000501

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Abstract (en)
A hot plate that does not expand much, has superior adhesion, and is provided with a conductive pattern layer having a large specific resistance. The hot plate 3 uses a ceramic nitride substrate 9, which includes conductive patterns 10, 10a. The conductive pattern layers 10, 10a is formed from ruthenium oxide, bismuth or its oxide, glass frit, and noble metal grains. <IMAGE>

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IPC 8 full level
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